

Tool ID: 706
Tool Location: 103

Equipment Information Sheet

Hamatech Hot Piranha

Manager: Sherri Ellis 607-255-2329
Backup: Garry Bordonaro 607-254-4936
Backup: Giovanni Sartorello 607-254-4853

Calls to staff phones will be automatically forwarded to their cell phones during accessible hours. At other times leave a message or send them an email.

SAFETY

- Stay away from chamber top during process
- Do not reach into chamber top during process
- Strong bases used in process
- Strong acids used in process

USAGE RESTRICTIONS

SCHEDULING/SIGN-UP RESTRICTIONS

Minimum Tool Time: 15 minutes

- None

MATERIALS COMPATIBILITY CATEGORY

| Tool Category 5: Class A and B Metals and Compounds | |
|---|---|
| Allowed | Not Allowed |
| Tool category 1/1E, 2, 3, and 4 materials | |
| Silicon Based Substrates and Films | |
| III/V compound Semiconductors | |
| Glass Substrates | |
| PECVD and ALD Films | |
| Cured organics and baked Photoresist | |
| CNF Class A, B, and Refractory metals | |
| Exposed Gold, Silver, Copper | |
| Alkali and Alkaline Compounds | |
| Organic/Biology Molecules prepared-w/salt buffers | |
| High Vapor Pressure Materials (Mg, Ca, Zn)* | * Some tool restrictions on high vapor pressure materials may apply |
| Soft organic materials | |

High Vapor Pressure Metals and Compounds are materials that have a vapor pressure above 1e-6 Torr at 400 C.

Additional Material Restrictions and Exceptions

- Whole wafers or masks sized for available chucks only
- No thick resist or organic layer stripping - piranha etch to be used for stripping residual material only!
- Check wafer for materials incompatible with cleaning chemistry to prevent substrate damage

Last Updated: 03/20/2025